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new e-mail

## MEMS Prototyping

In addition to CMOS, BiCMOS, SiGe and Silicon Photonic Integrated Circuits, CMP is offering several types of MEMS technologies for prototyping and low volume production: Integrated bulk micromachining technologies and specific surface micromachining technologies.

CMP distributes Process Design-Kits (PDK) for CMOS/BiCMOS IC's, Photonic IC's and MEMS' technologies. Each of them contains technology files, simulation models, design rules, standard cell libraries of the chosen technology. A copy of any requested design kit can be sent to the customer after a non-disclosure agreement (NDA) with CMP.

Customer request and support are provided through our Web interfaces:

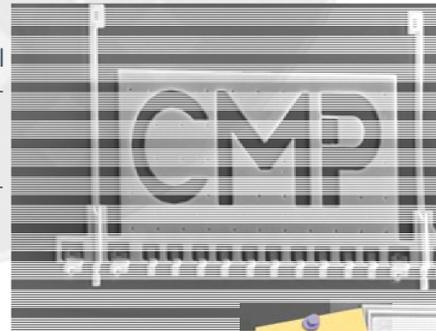
**Design-Kit Request Form**-><http://cmp3.imag.fr/products/DK/dkr>

**Design-Kit Support Center**-><https://cmp3.imag.fr/support>

Contact us

- Request Form: **Sylvaine EYRAUD** [[Sylvaine.Eyraud@mycmp.fr](mailto:Sylvaine.Eyraud@mycmp.fr)]  
- Support Center.: **Christelle RABACHE** [[Christelle.Rabache@mycmp.fr](mailto:Christelle.Rabache@mycmp.fr)]

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### ams 0.35µm CMOS Bulk Micromachining



This technology is based on standard CMOS or BiCMOS process allowing integration of MEMS sensor and front-end electronic on the same die for better signal to noise ratio. Suspended passive devices or structures can be made with this technology. Applications include thermal inertial sensors and infrared sensors.

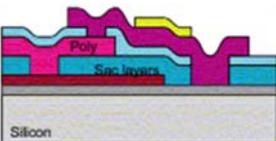
**ams 0.35µm CMOS Bulk Micromachining front-side:** 650€/mm<sup>2</sup> + 3700€ for 10 dies

**ams 0.35µm CMOS Bulk Micromachining back-side,** price under request.

### MEMSCAP PolyMUMPS, SOIMUMPS, PiezoMUMPS

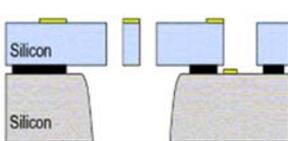
Available through CMP since 1998, the Multi-User MEMS Processes (MUMPS) is a Multi Project Wafer program offering customers cost-effective access to MEMS prototyping and low volume production through three different processes: PolyMUMPS, SOIMUMPS and PiezoMUMPS. These technologies allow the realization of various MEMS devices: 3900€ for 15 identical chips, (1mm x 1mm, fixed size).

#### PolyMUMPS



Polysilicon/gold surface micromachining

#### SOIMUMPS



SOIMUMPS + piezoelectric layer

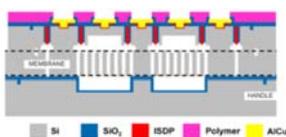
#### PiezoMUMPS



On-chip suspended membrane with piezoresistors

Deep Reactive Ion Etching on Silicon on Insulator

### Teledyne DALSA TDSI MIDIS™



**MIDIS™** MEMS technology is offered to CMP user community thanks to an agreement and partnership with CMC. The MEMS Integrated Design for Inertial Sensors (MIDIS™) platform is designed to provide a standard process for manufacturing accelerometers and gyroscopes:

8000€ (4mm x 4mm).

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Contact us

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- Azedine MANAA [[Azedine.Manaa@mycmp.fr](mailto:Azedine.Manaa@mycmp.fr)]

#### Packaging:

Optical resin/Chip On Board (COB)/Thermal solutions/Metallic package/Hermetic package.



#### Partnership:



\*Notes:  
- Minimum charges apply on most MPW services (invoice of a minimum surface).  
- Degressive prices are applied to most MPW service - check on the web site.  
- Prices may change without notice.